HUF75333G3, HUF75333P3, HUF75333S3S, HUF75333S3

66A, 55V, 0.016 Ohm. N-Channel UltraFET Power MOSFETs

These N-Channel power MOSFETs are manufactured using the innovative UltraFET® process. This advanced process technology achieves the lowest possible on-resistance per silicon area, resulting in outstanding performance. This device is capable of withstanding high energy in the avalanche mode and the diode exhibits very low reverse recovery time and stored charge. It was designed for use in applications where power efficiency is important, such as switching regulators, switching convertors, motor drivers, relay drivers, low-voltage bus switches, and power management in portable and battery-operated products. .

Features

- 66A, 55V
- Simulation Models
  - Temperature Compensated PSPICE® and SABER™ Models
  - SPICE and SABER Thermal Impedance Models Available on the WEB at: www.fairchildsemi.com
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- Related Literature
  - TB334, “Guidelines for Soldering Surface Mount Components to PC Boards”

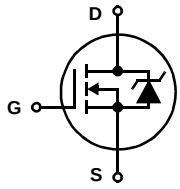
Formerly developmental type TA75333

Ordering Information

PART NUMBER	PACKAGE	BRAND
HUF75333G3	TO-247	75333G
HUF75333P3	TO-220AB	75333P
HUF75333S3S	TO-263AB	75333S
HUF75333S3	TO-262AA	75333S

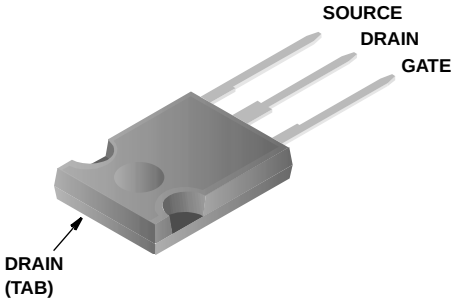
NOTE: When ordering, use the entire part number. Add the suffix T to obtain the TO-263AB variant in tape and reel, e.g., HUF75333S3ST.

Symbol

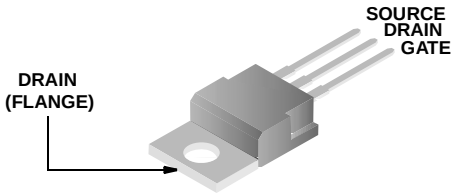


Packaging

JEDEC STYLE TO-247



JEDEC TO-220AB



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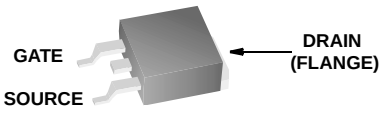
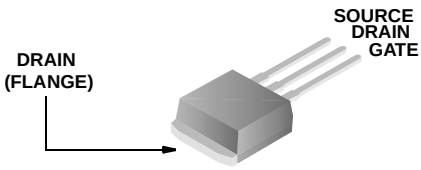


JEDEC TO-262ABA



Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

		UNITS
Drain to Source Voltage (Note 1) . . . . . V_{DSS}	55	V
Drain to Gate Voltage (R_{GS} = 20kΩ) (Note 1) . . . . . V_{DGR}	55	V
Gate to Source Voltage . . . . . V_{GS}	±20	V
Drain Current		
Continuous (Figure 2). . . . . I_D	66	A
Pulsed Drain Current . . . . . I_{DM}	Figure 4	
Pulsed Avalanche Rating . . . . . E_{AS}	Figures 6, 14, 15	
Power Dissipation . . . . . P_D	150	W
Derate Above 25^oC	1	$W/^oC$
Operating and Storage Temperature . . . . . T_J, T_{STG}	-55 to 175	^oC
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s. . . . . T_L	300	^oC
Package Body for 10s, See Techbrief 334 . . . . . T_{pkg}	260	^oC

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^oC$ to 150^oC.

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
OFF STATE SPECIFICATIONS							
Drain to Source Breakdown Voltage	BV_{DSS}	I_D = 250μA, V_{GS} = 0V (Figure 11)		55	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 50V, V_{GS} = 0V		-	-	1	μA
		V_{DS} = 45V, V_{GS} = 0V, $T_C = 150^oC$		-	-	250	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±20V		-	-	±100	nA
ON STATE SPECIFICATIONS							
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, I_D = 250μA (Figure 10)		2	-	4	V
Drain to Source On Resistance	$r_{DS(ON)}$	I_D = 66A, V_{GS} = 10V (Figure 9)		-	0.013	0.016	Ω
THERMAL SPECIFICATIONS							
Thermal Resistance Junction to Case	$R_{\theta JC}$	(Figure 3)		-	-	1	$^oC/W$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	TO-247		-	-	30	$^oC/W$
		TO-220, TO-263		-	-	62	$^oC/W$
SWITCHING SPECIFICATIONS (V_{GS} = 10V)							
Turn-On Time	t_{ON}	V_{DD} = 30V, $I_D \cong$ 66A, R_L = 0.455Ω, V_{GS} = 10V, R_{GS} = 6.8Ω		-	-	100	ns
Turn-On Delay Time	$t_{d(ON)}$			-	12	-	ns
Rise Time	t_r			-	55	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	11	-	ns
Fall Time	t_f			-	25	-	ns
Turn-Off Time	t_{OFF}			-	-	55	ns
GATE CHARGE SPECIFICATIONS							
Total Gate Charge	$Q_{g(TOT)}$	V_{GS} = 0V to 20V	V_{DD} = 30V, $I_D \cong$ 66A, R_L = 0.455Ω $I_{g(REF)}$ = 1.0mA (Figure 13)	-	70	85	nC
Gate Charge at 10V	$Q_{g(10)}$	V_{GS} = 0V to 10V		-	40	50	nC
Threshold Gate Charge	$Q_{g(TH)}$	V_{GS} = 0V to 2V		-	2.5	3.0	nC
Gate to Source Gate Charge	Q_{gs}			-	6.2	-	nC
Gate to Drain "Miller" Charge	Q_{gd}			-	16	-	nC

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
CAPACITANCE SPECIFICATIONS						
Input Capacitance	C_{ISS}	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz (Figure 12)	-	1300	-	pF
Output Capacitance	C_{OSS}		-	480	-	pF
Reverse Transfer Capacitance	C_{RSS}		-	115	-	pF

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	I_{SD} = 66A	-	-	1.25	V
Reverse Recovery Time	t_{rr}	I_{SD} = 66A, dI_{SD}/dt = 100A/µs	-	-	75	ns
Reverse Recovered Charge	Q_{RR}	I_{SD} = 66A, dI_{SD}/dt = 100A/µs	-	-	140	nC

Typical Performance Curves

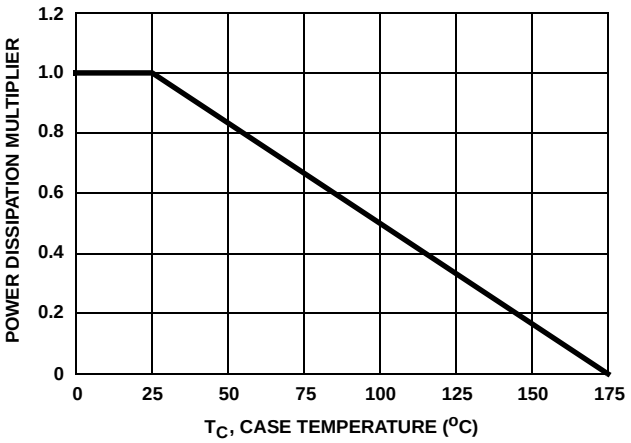


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

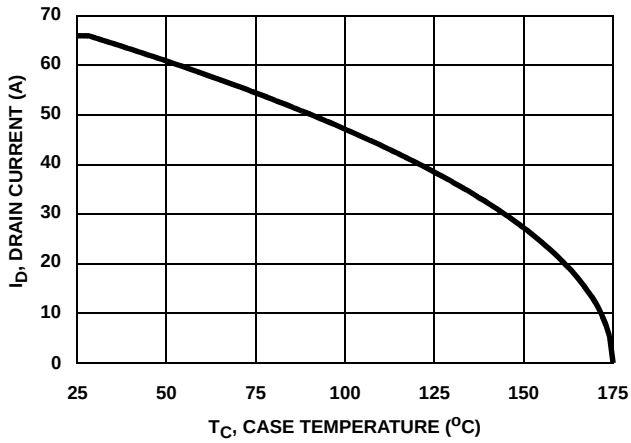


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

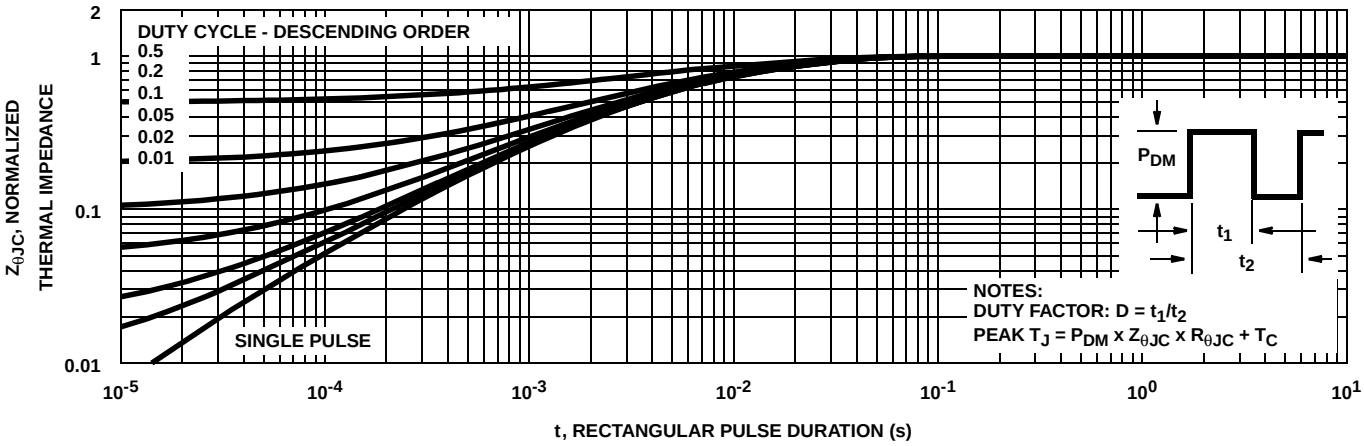


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE